

# SKiiP 23NAB12T4V1



MiniSKiiP® 2

3-phase bridge rectifier +  
brake chopper + 3-phase  
bridge inverter  
SKiiP 23NAB12T4V1

## Features

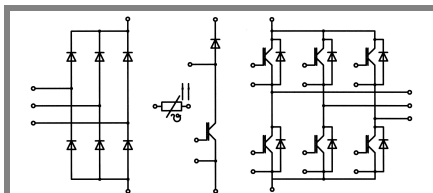
- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

## Typical Applications

- Inverter up to 14 kVA
- Typical motor power 7,5 kW

## Remarks

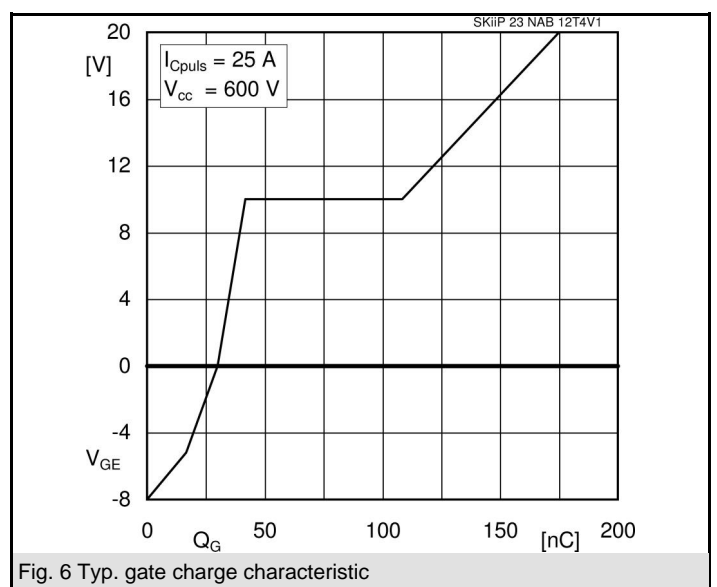
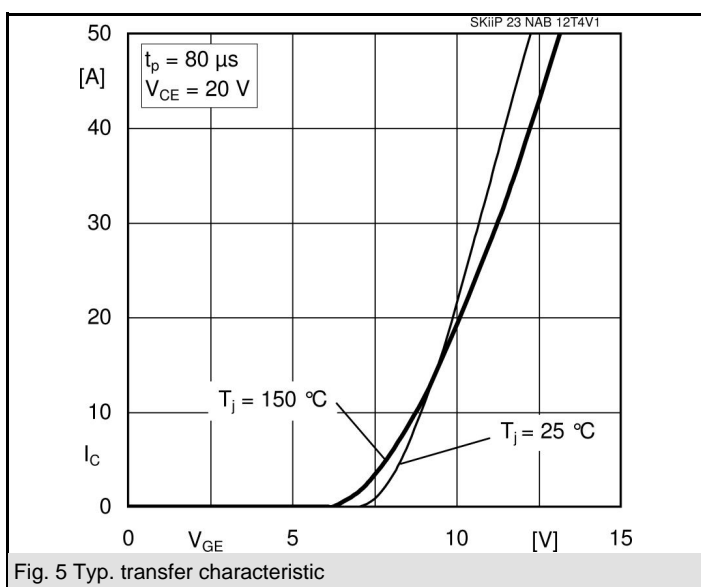
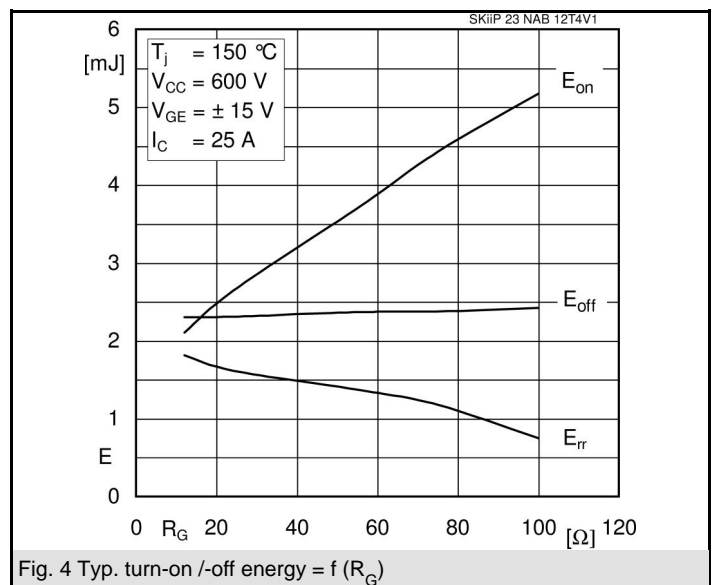
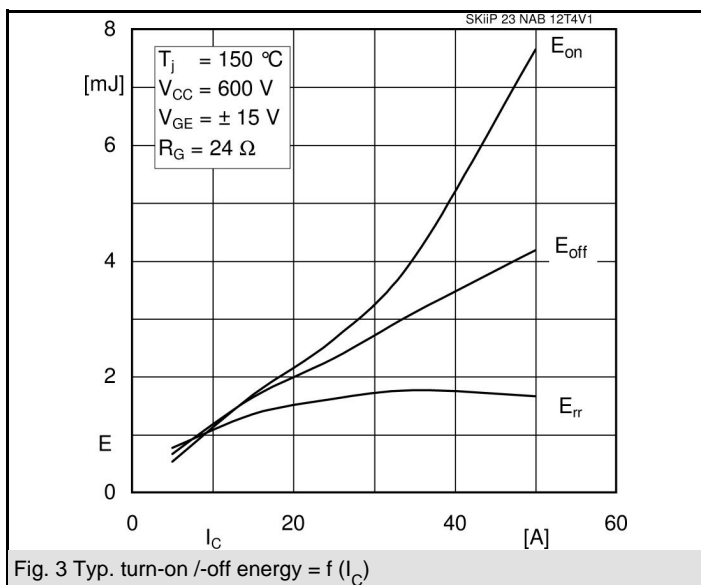
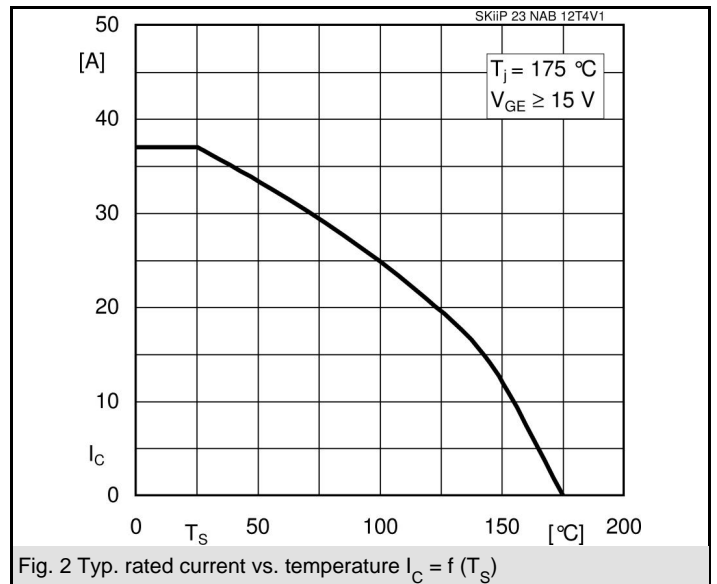
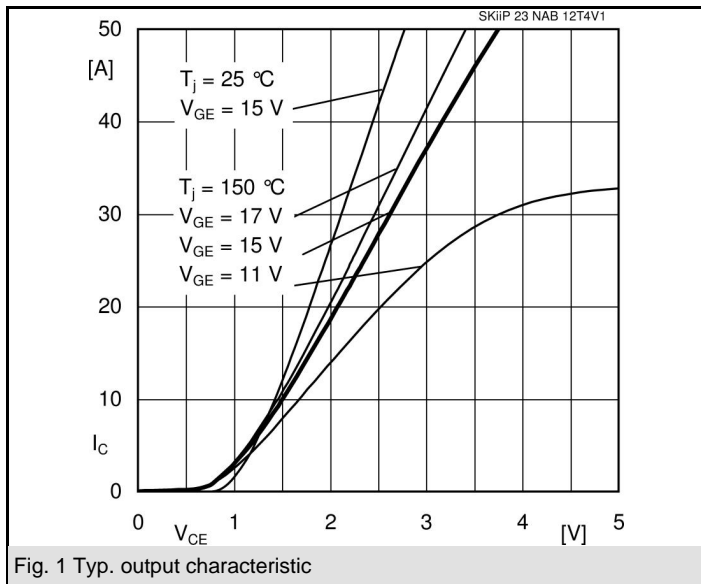
- $V_{CEsat}$ ,  $V_F$  = chip level value
- Case temp. limited to  $T_C = 125^\circ\text{C}$  max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_{j \leq 150}$  (recomm.  $T_{op} = -40 \dots +150^\circ\text{C}$ )



NAB

Absolute Maximum Ratings		$T_S = 25^\circ\text{C}$ , unless otherwise specified		
Symbol	Conditions	Values	Units	
<b>IGBT - Inverter, Chopper</b>				
$V_{CES}$	$T_S = 25 (70)^\circ\text{C}$	1200	V	
$I_C$		37 (30)	A	
$I_{CRM}$		75	A	
$V_{GES}$		$\pm 20$	V	
$T_j$		- 40 ... + 175	$^\circ\text{C}$	
<b>Diode - Inverter, Chopper</b>				
$I_F$	$T_S = 25 (70)^\circ\text{C}$	30 (26)	A	
$I_{FRM}$		75	A	
$T_j$		- 40 ... + 175	$^\circ\text{C}$	
<b>Diode - Rectifier</b>				
$V_{RRM}$	$T_S = 70^\circ\text{C}$	1600	V	
$I_F$		46	A	
$I_{FSM}$		$t_p = 10 \text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	370	A
$i^2t$		$t_p = 10 \text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	680	$\text{A}^2\text{s}$
$T_j$		- 40 ... + 150	$^\circ\text{C}$	
<b>Module</b>				
$I_{RMS}$	per power terminal (20 A / spring)	40	A	
$T_{stg}$		- 40 ... + 125	$^\circ\text{C}$	
$V_{isol}$	AC, 1 min.	2500	V	

Characteristics		$T_S = 25^\circ\text{C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>IGBT - Inverter, Chopper</b>					
$V_{CEsat}$	$I_{Cnom} = 25 \text{ A}, T_j = 25 (150)^\circ\text{C}$		1,85 (2,25)	2,05 (2,45)	V
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 1 \text{ mA}$	5	5,8	6,5	V
$V_{CE(TO)}$	$T_j = 25 (150)^\circ\text{C}$		0,8 (0,7)	0,9 (0,8)	V
$r_T$	$T_j = 25 (150)^\circ\text{C}$		42 (62)	46 (66)	m $\Omega$
$C_{ies}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		1,4		nF
$C_{oes}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,12		nF
$C_{res}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,085		nF
$R_{th(j-s)}$	per IGBT		1,2		K/W
$t_{d(on)}$	under following conditions		28		ns
$t_r$	$V_{CC} = 600 \text{ V}, V_{GE} = \pm 15 \text{ V}$		40		ns
$t_{d(off)}$	$I_{Cnom} = 25 \text{ A}, T_j = 150^\circ\text{C}$		295		ns
$t_f$	$R_{Gon} = R_{Goff} = 24 \Omega$		68		ns
$E_{on}$	inductive load		2,65		mJ
$E_{off}$			2,3		mJ
<b>Diode - Inverter, Chopper</b>					
$V_F = V_{EC}$	$I_{Fnom} = 25 \text{ A}, T_j = 25 (150)^\circ\text{C}$		2,4 (2,45)	2,75 (2,8)	V
$V_{(TO)}$	$T_j = 25 (150)^\circ\text{C}$		1,3 (0,9)	1,5 (1,1)	V
$r_T$	$T_j = 25 (150)^\circ\text{C}$		44 (62)	50 (68)	m $\Omega$
$R_{th(j-s)}$	per diode		1,52		K/W
$I_{RRM}$	under following conditions		23,6		A
$Q_{rr}$	$I_{Fnom} = 25 \text{ A}, V_R = 600 \text{ V}$		3,7		$\mu\text{C}$
$E_{rr}$	$V_{GE} = 0 \text{ V}, T_j = 150^\circ\text{C}$		1,6		mJ
	$di_F/dt = 850 \text{ A}/\mu\text{s}$				
<b>Diode - Rectifier</b>					
$V_F$	$I_{Fnom} = 25 \text{ A}, T_j = 25^\circ\text{C}$		1,1		V
$V_{(TO)}$	$T_j = 150^\circ\text{C}$		0,8		V
$r_T$	$T_j = 150^\circ\text{C}$		13		m $\Omega$
$R_{th(j-s)}$	per diode		1,25		K/W
<b>Temperature Sensor</b>					
$R_{ts}$	3 %, $T_r = 25 (100)^\circ\text{C}$		1000(1670)		$\Omega$
<b>Mechanical Data</b>					
w			65		g
$M_s$	Mounting torque	2		2,5	Nm



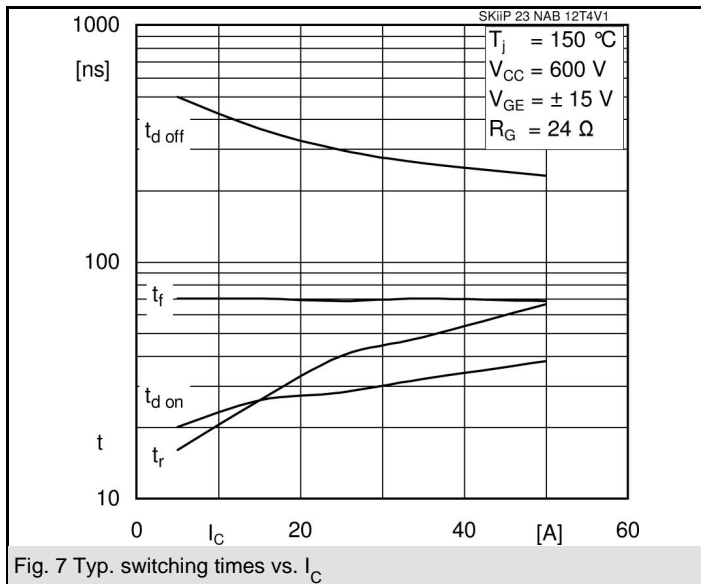


Fig. 7 Typ. switching times vs.  $I_C$

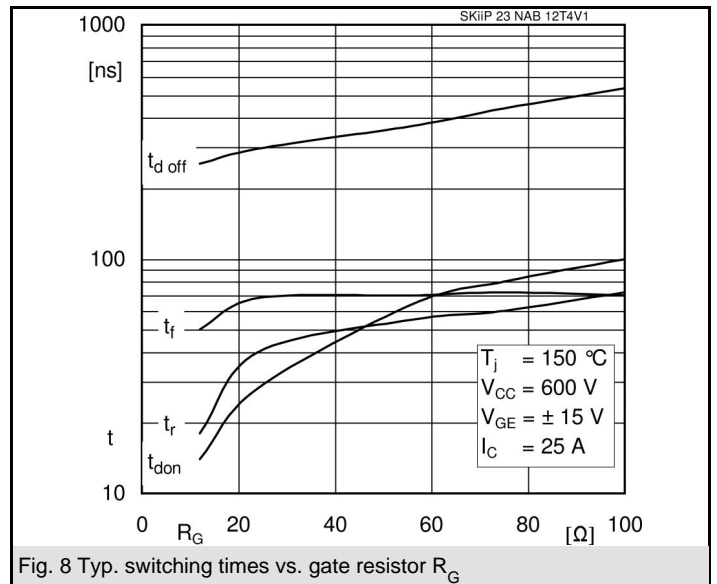


Fig. 8 Typ. switching times vs. gate resistor  $R_G$

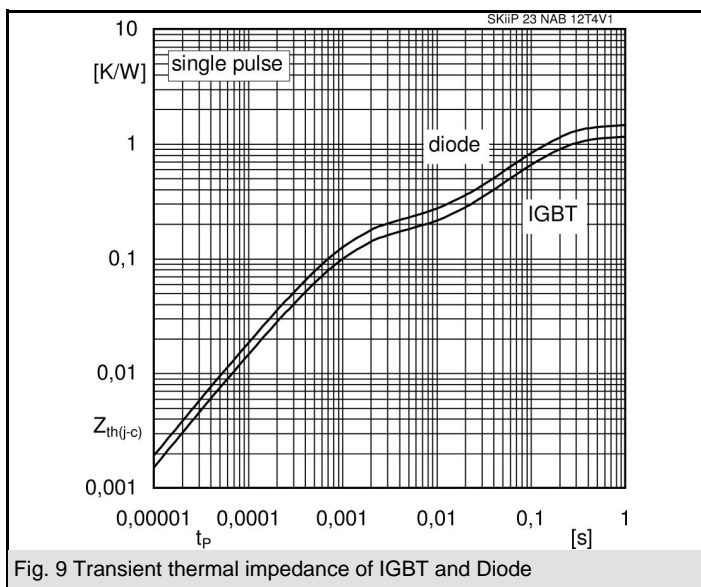


Fig. 9 Transient thermal impedance of IGBT and Diode

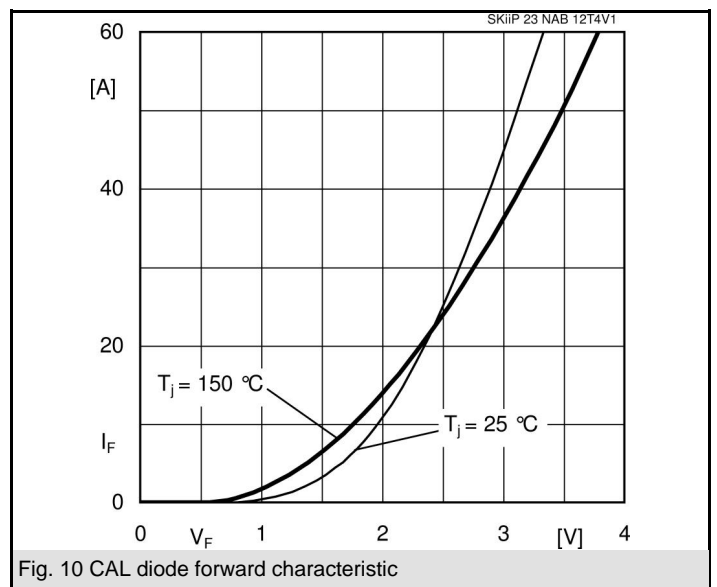


Fig. 10 CAL diode forward characteristic

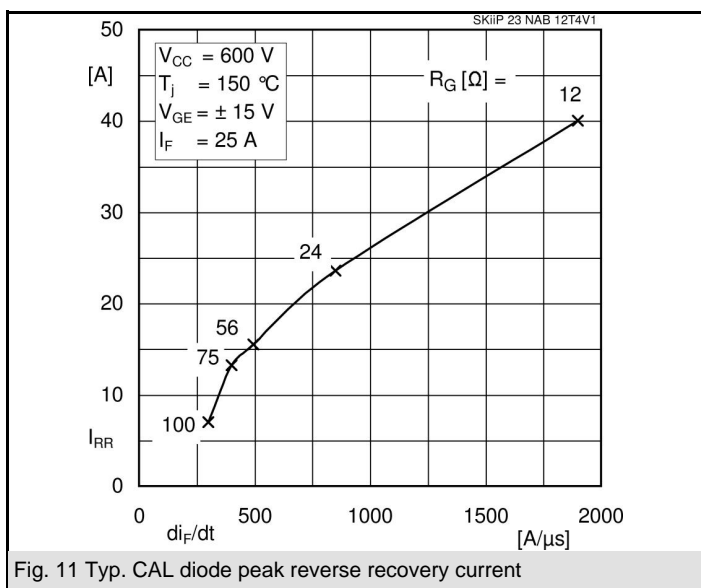


Fig. 11 Typ. CAL diode peak reverse recovery current

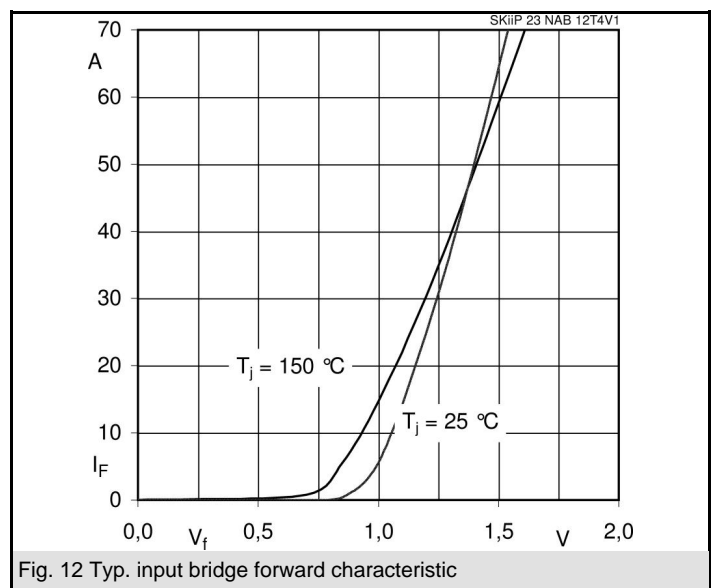
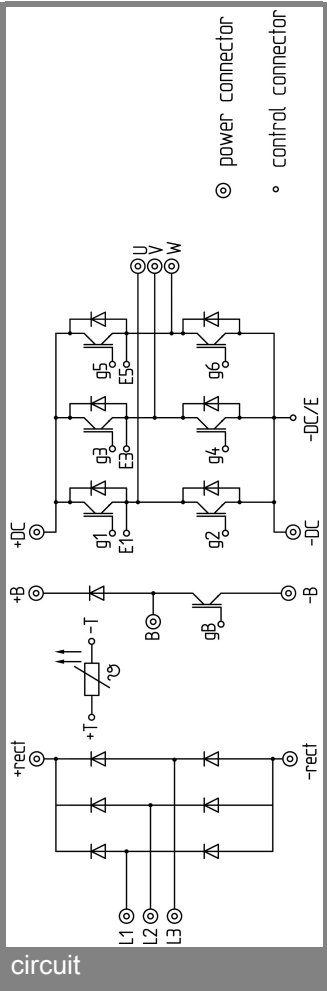
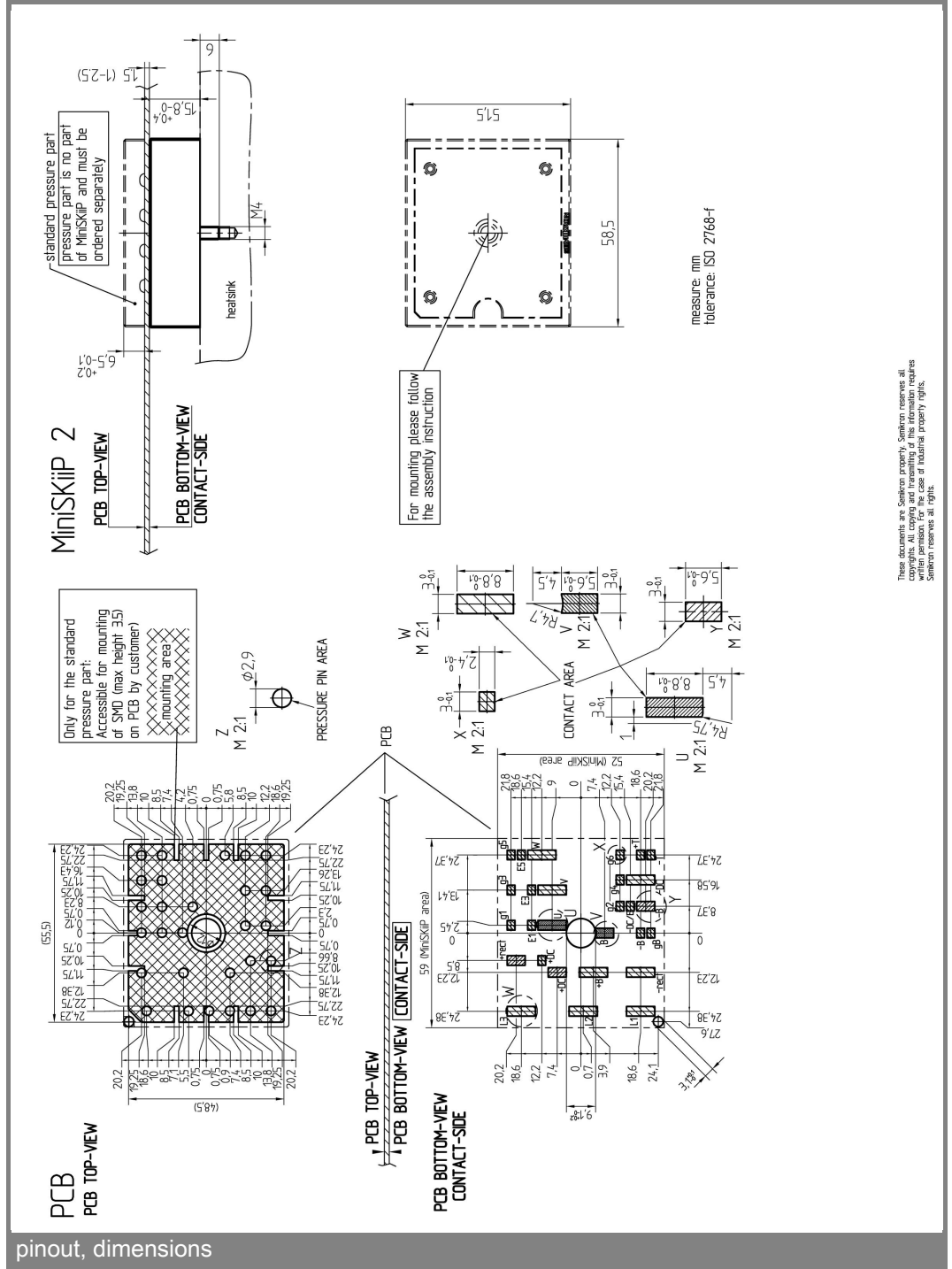


Fig. 12 Typ. input bridge forward characteristic



circuit



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